

HSB276S

Silicon Schottky Barrier Diode for Detector and Mixer

REJ03G0133-0100Z

(Previous: ADE-208-780)

Rev.1.00 Nov.10.2003

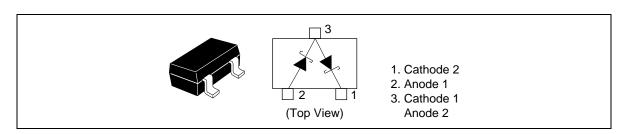
Features

- High forward current, Low capacitance.
- HSB276S which is interconnected in series configuration is designed for balanced mixer use.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSB276S	C2	CMPAK

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Reverse voltage	V_R	3	V	
Average rectified current	lo ^{*1}	30	mA	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Note: 1. Per one device

Electrical Characteristics *1

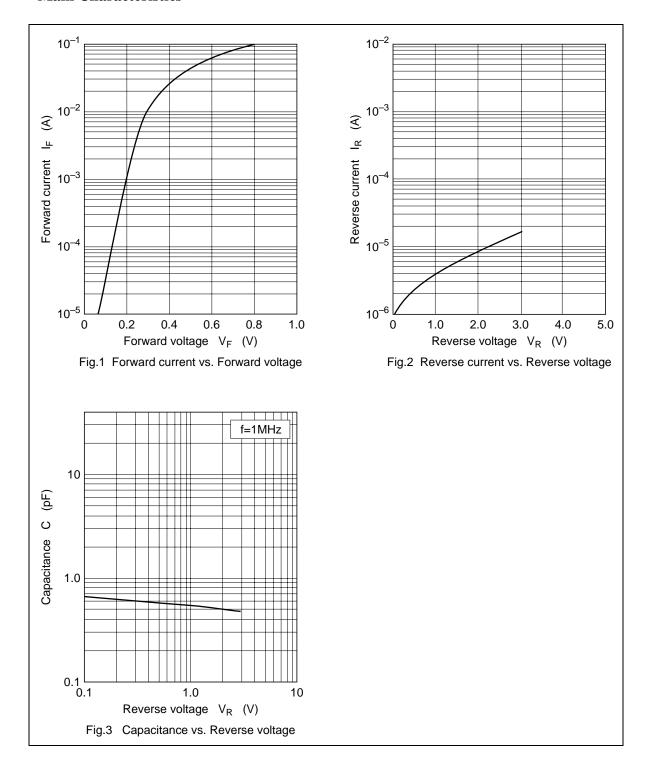
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V_R	3	_	_	V	I _R = 1 mA
Reverse current	I _R	_		50	μА	V _R = 0.5 V
Forward current	I _F	35	_	_	mA	$V_F = 0.5 \text{ V}$
Capacitance	С	_		0.9	pF	V _R = 0.5 V, f = 1 MHz
Capacitance deviation	ΔC	_	_	0.1	pF	$V_R = 0.5 V, f = 1 MHz$
ESD-Capability *2	_	30	_	_	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.

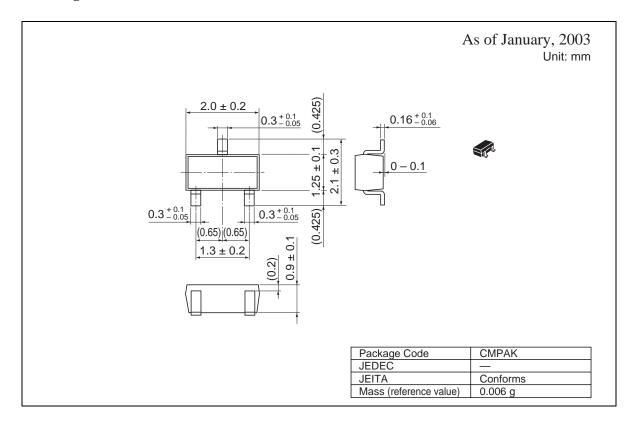
Note: 1. Per one device

2. Failure criterion ; $I_R \geq 100~\mu A$ at $V_R = 0.5~V$

Main Characteristics



Package Dimensions



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